NUF2030XV6, NUF2042XV6

USB Upstream Terminator with ESD Protection

These devices are designed for applications requiring **Line Termination**, **EMI Filtering** and **ESD Protection**. They are intended for use in upstream USB ports, cellular phones, wireless equipment and computer applications. These devices offer an integrated solution in a small package (SOT−563) reducing PCB space and cost.

Features:

- Provides USB Line Termination, Filtering and ESD Protection
- Single IC Offers Cost Savings
- Bidirectional EMI Filtering Prevents Noise from Entering/Leaving the System
- Compliance with IEC61000−4−2 (Level 4)
  8 kV (Contact)
  15 kV (Air)
- ESD Ratings: Machine Model = C
  Human Body Model = 3B
- These are Pb−Free Devices

Benefits:

- SOT−563 Package Minimizes PCB Space
- Integrated Circuit Increases System Reliability versus Discrete Component Implementation
- TVs Devices Provide ESD Protection That is Better than a Discrete Implementation because the Small IC minimizes Parasitic Inductances

Typical Applications:

- USB Hubs
- Computer Peripherals Using USB

MAXIMUM RATINGS (T_A = 25°C)

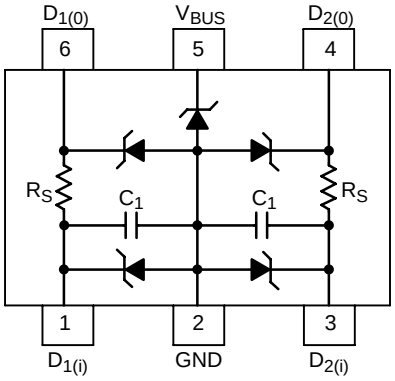
Rating	Symbol	Value	Unit
Steady State Power	P_D	225	mW
Maximum Junction Temperature	$T_{J(max)}$	125	°C
Operating Temperature Range	T_J	−55 to +125	°C
Storage Temperature Range	T_{stg}	−55 to +125	°C
Lead Solder Temperature (10 second duration)	T_L	260	°C

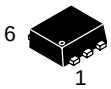
Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

ON Semiconductor®

http://onsemi.com

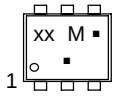
CIRCUIT DESCRIPTION





SOT−563
CASE 463A

MARKING DIAGRAM



xx = Specific Device Code
(see table on page 5)
M = Month Code
▪ = Pb−Free Package
(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

© Semiconductor Components Industries, LLC, 2005

July, 2005 − Rev. 2

Publication Order Number:
NUF2030XV6/D

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Device	V_{RWM} (V)	V_{BR} @ 1 mA (V)			I_R @ 3.3 V (nA)			Line Capacitance Vdc = 2.5 V f = 1 MHz (pF) (Note 1)			Series Resistor R_S (Ω)		
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max
NUF2030XV6T1	5.25	5.6	6.8	8.0	–	10	100	–	30	36	17.6	22	26.4
NUF2042XV6T1	5.25	5.6	6.8	8.0	–	10	100	37.6	42	56.4	17.6	22	26.4

1. Measured between pins 1, 3, 4, 6 and ground with pin 5 also grounded.
2. For other resistance value (e.g. 33 Ω), please contact your local ON Semiconductor sales representative.

TYPICAL CHARACTERISTICS

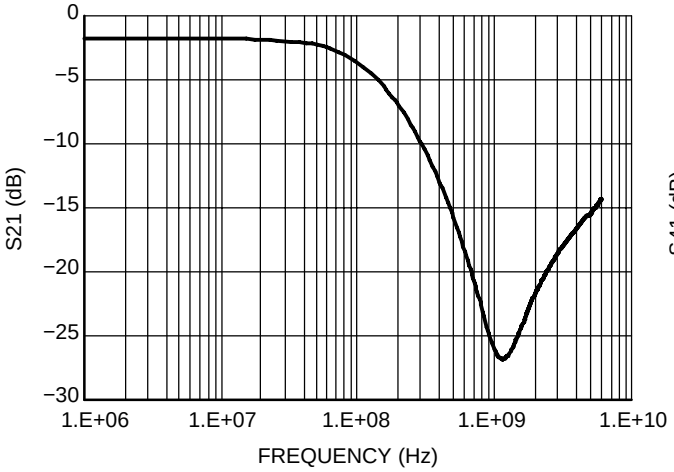


Figure 1. Insertion Loss Characteristics (NUF2030)

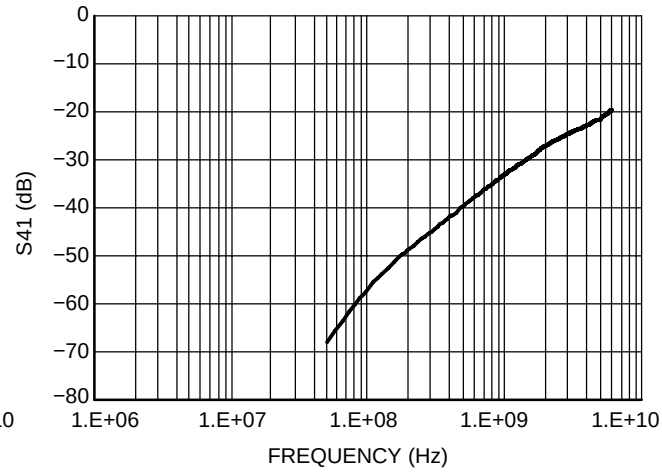


Figure 2. Analog Cross−Talk (NUF2030)

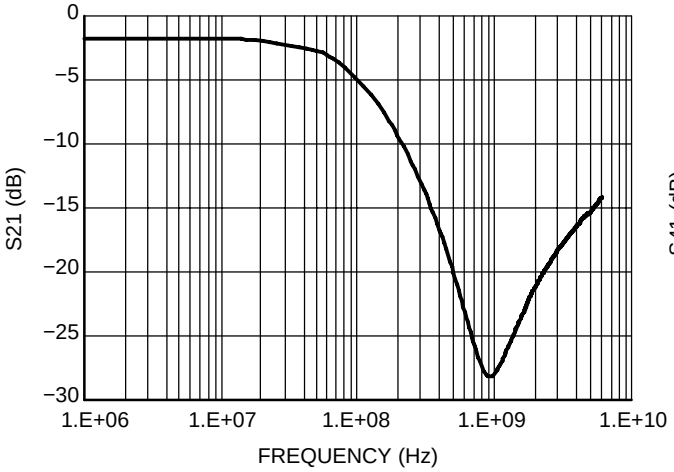


Figure 3. Insertion Loss Characteristics (NUF2042)

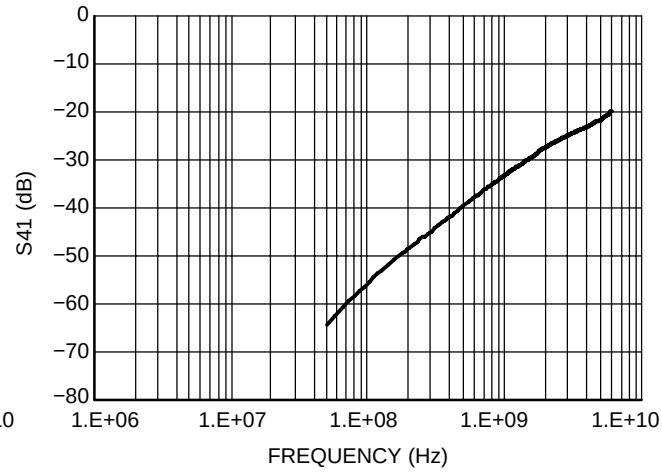


Figure 4. Analog Cross−Talk (NUF2042)

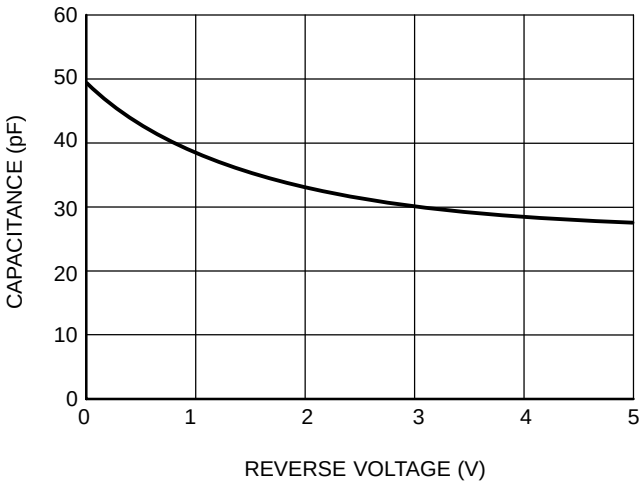


Figure 5. Typical Capacitance (NUF2030)

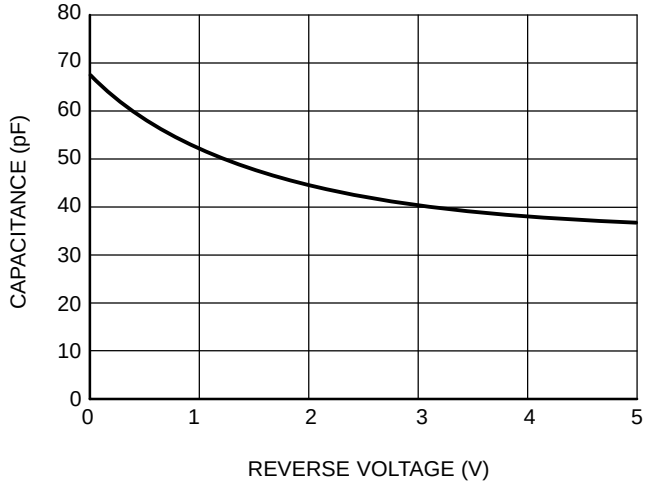


Figure 6. Typical Capacitance (NUF2042)

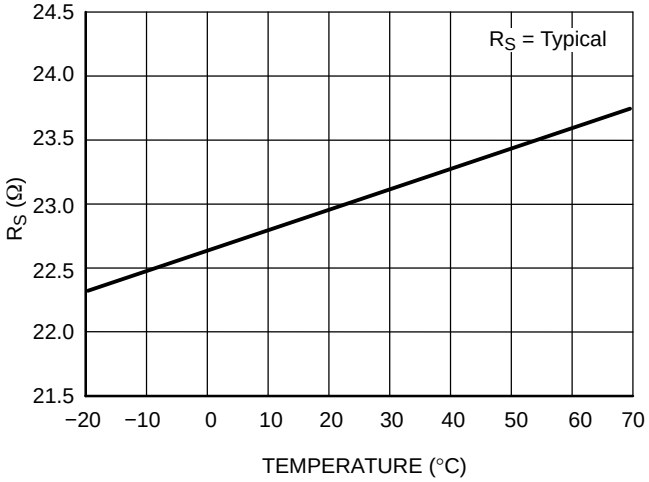
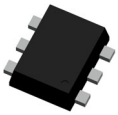


Figure 7. R_S versus Temperature (NUF2030 and NUF2042)

ORDERING INFORMATION

Device	Device Marking	Package	Shipping†
NUF2030XV6T1	30	SOT−563*	4000 / Tape & Reel
NUF2030XV6T1G	30	SOT−563*	4000 / Tape & Reel
NUF2042XV6T1	22	SOT−563*	4000 / Tape & Reel
NUF2042XV6T1G	22	SOT−563*	4000 / Tape & Reel

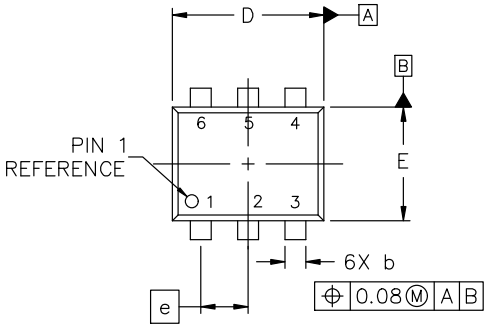
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
*These packages are inherently Pb−Free.



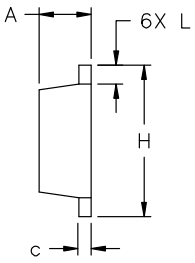
SOT−563−6 1.60x1.20x0.55, 0.50P
CASE 463A
ISSUE J

DATE 15 FEB 2024

NOTES:
1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5−2018.
2. ALL DIMENSION ARE IN MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

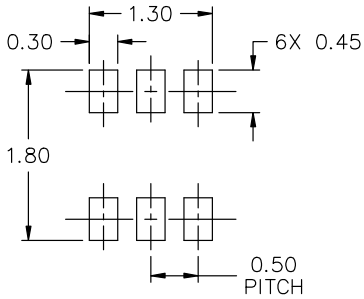


TOP VIEW



SIDE VIEW

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.50	0.55	0.60
b	0.17	0.22	0.27
c	0.08	0.13	0.18
D	1.50	1.60	1.70
E	1.10	1.20	1.30
e	0.50 BSC		
H	1.50	1.60	1.70
L	0.10	0.20	0.30



RECOMMENDED MOUNTING FOOTPRINT*

* FOR ADDITIONAL INFORMATION ON OUR Pb−FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

STYLE 1:
PIN 1. EMITTER 1
2. BASE 1
3. COLLECTOR 2
4. EMITTER 2
5. BASE 2
6. COLLECTOR 1

STYLE 2:
PIN 1. EMITTER 1
2. EMITTER 2
3. BASE 2
4. COLLECTOR 2
5. BASE 1
6. COLLECTOR 1

STYLE 3:
PIN 1. CATHODE 1
2. CATHODE 1
3. ANODE/ANODE 2
4. CATHODE 2
5. CATHODE 2
6. ANODE/ANODE 1

STYLE 4:
PIN 1. COLLECTOR
2. COLLECTOR
3. BASE
4. EMITTER
5. COLLECTOR
6. COLLECTOR

STYLE 5:
PIN 1. CATHODE
2. CATHODE
3. ANODE
4. ANODE
5. CATHODE
6. CATHODE

STYLE 6:
PIN 1. CATHODE
2. ANODE
3. CATHODE
4. CATHODE
5. CATHODE
6. CATHODE

STYLE 7:
PIN 1. CATHODE
2. ANODE
3. CATHODE
4. CATHODE
5. ANODE
6. CATHODE

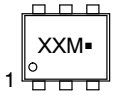
STYLE 8:
PIN 1. DRAIN
2. DRAIN
3. GATE
4. SOURCE
5. DRAIN
6. DRAIN

STYLE 9:
PIN 1. SOURCE 1
2. GATE 1
3. DRAIN 2
4. SOURCE 2
5. GATE 2
6. DRAIN 1

STYLE 10:
PIN 1. CATHODE 1
2. N/C
3. CATHODE 2
4. ANODE 2
5. N/C
6. ANODE 1

STYLE 11:
PIN 1. EMITTER 2
2. BASE 2
3. COLLECTOR 1
4. EMITTER 1
5. BASE 1
6. COLLECTOR 2

GENERIC MARKING DIAGRAM*



XX = Specific Device Code
M = Month Code
▪ = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

DOCUMENT NUMBER:	98AON11126D	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped “CONTROLLED COPY” in red.
DESCRIPTION:	SOT−563−6 1.60x1.20x0.55, 0.50P	PAGE 1 OF 1

onsemi and onsemi are trademarks of Semiconductor Components Industries, LLC dba **onsemi** or its subsidiaries in the United States and/or other countries. **onsemi** reserves the right to make changes without further notice to any products herein. **onsemi** makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. **onsemi** does not convey any license under its patent rights nor the rights of others.

onsemi, onsemi, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "**onsemi**" or its affiliates and/or subsidiaries in the United States and/or other countries. **onsemi** owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of **onsemi**'s product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent−Marking.pdf. **onsemi** reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as−is" and **onsemi** makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:
Technical Library: www.onsemi.com/design/resources/technical−documentation
onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support
For additional information, please contact your local Sales Representative at
www.onsemi.com/support/sales